[0070] In non-limiting example shown in FIG. **7**, drive layer **206** of input structure **200** may be disposed over and coupled to a portion of base portion **106** of electronic device **100**. Drive layer **206**, as shown in FIG. **7**, may be coupled to base portion **106** of electronic device **100** at each corner of drive layer **206**. Adhesive **230** may be used to couple drive layer **206** to base portion **106**. Similar to FIG. **6**, in the example shown in FIG. **7**, stack-up of input structure **200** may be supported by base portion **106** of casing **102** of electronic device **100**. By coupling drive layer **206** to base portion **106** only at the corners of drive layer **206**, the material used for coupling input structure **200** within casing **102** may be reduced. Additionally, by coupling drive layer **206** to base portion **106** only at the corners of drive layer **206**, sense layer **204** and compliant layer **208** may have increased deflection when a user provides an input to electronic device **100** by applying a force. The increase deflection may ensure electronic device **100** receives the input provided by the user. Although shown in FIG. **7** as utilizing adhesive **230** to couple drive layer **206** to base portion **106**, it is understood that other suitable coupling and/or bonding components may be used. In non-limiting examples, drive layer **206** may be coupled to base portion **106** using tape, lamination and so on.

[0071] As discussed herein, sense layer **204** and drive layer **206** of input structure **200** may capacitively detect a force (F) resulting from a user input. FIG. **8** shows a portion of sense layer **204**, drive layer **206** and compliant layer **208** positioned therebetween. In the non-limiting example shown in FIG. **8**, sense layer **204** may be formed from an array of sensor pixels **232**, and drive layer **206** may be formed from an array of drive pixels **234**. "Pixel," as used herein, does not necessarily refer to a pixel of a display device (e.g., an independently illuminable region of a display) but instead to a discrete electrode or other discrete electrical element that forms a portion of a sensor or sensing area.

[0072] Each sensor pixel **232** of sense layer **204** may correspond to a single drive pixel **234** of drive layer **206**, where the corresponding pixels of sense layer **204** and drive layer **206** may be aligned and positioned on opposite sides of compliant layer **208**. Thus, each pair of sense and drive pixels may be considered a capacitor. As shown in the non-limiting example embodiment, sensor pixels **232** and drive pixels **234** may be aligned within the respective layer and may be positioned and/or coupled directly to compliant layer **208**. In another non-limiting example, sensor pixels **232** of sense layer **204** and drive pixels **234** of drive layer **206** may be coupled to a substrate (not shown) for positioning the electrodes on a separate and distinct layer of input structure **200**. As discussed herein, a single sensor pixel **232** and corresponding drive pixel **234** may be used by a single input component or button of input structure **200**, or an array of sensor pixels **232** and corresponding drive pixels **234** may be used by a single input component or button. The change in capacitance may be detected when the distance between the sensor pixels **232** and drive pixels **234** varies as a result of deformation in the contact portion **104**. The change in capacitance may indicate a force applied by a user providing an input to electronic device **100**. Additionally, a location in which the change in capacitance occurs may indicate the location of the force applied by the user. That is, embodiments described herein may localize a force by determining a pair of pixels underlying or otherwise corresponding to a location at which the force is applied, for example because the change in capacitance is greatest at that intersection. Thus, embodiments described herein may sense not only force but also a location at which a force is applied and thus, a location of a touch or force. In yet another embodiment, only one layer or array of pixels may be used; the pixels may be mutually capacitive with respect to adjacent pixels. Changes in this mutual capacitance may be used to detect either or both of a location and amount of force, as described above

[0073] In another non-limiting example, as shown in FIG. **9**, sense layer **204** may be formed from multiple sensor capacitive columns **236** arranged in a first direction. Additionally in the non-limiting example, drive layer **206** may be formed from multiple drive capacitive rows **238** arranged in a second direction, distinct from the first direction. Although not shown, the respective capacitive columns **236** and capacitive rows **238** forming sense layer **204** and drive layer **206** of input structure **200** may be separated by compliant layer **208**, as discussed herein. When sense layer **204** utilizes sensor capacitive columns **236**, and drive layer **206** is formed from drive capacitive rows **238**, a change in capacitance at an intersection of sensor capacitive columns **236** and drive capacitive rows **238** may indicate a force applied by a user providing an input to electronic device **100**. To detect the change in capacitance at an intersection, a charge or current may be repeatedly provided through each of sensor capacitive columns **236** or drive capacitive rows **238** in a predetermined sequence. When a detected capacitance varies from a steady or uncompressed state capacitance, the location and/or amount of the force applied to sense layer **204** may be detected. A location of touch may be determined in a similar fashion to that previously described with respect to FIG. **8**; e.g., by determining a location corresponding to an intersection of a drive row and sense column experiencing or reporting a greatest change in capacitance.

[0074] FIG. **10** shows a top view of electronic device **100** including input structure **200**. As shown in FIG. **10** and discussed herein with respect to FIGS. **2** and **3**, casing **102** may have a group of micro-perforations or holes **220** (shown in phantom) formed through contact portion **104**. In the non-limiting example, holes **220** may be formed through contact portion **104** in predetermined input areas **202***a*, **202***b*, **202***c*, **202***d* of electronic device **100**. Each of the input areas **202***a*, **202***b*, **202***c*, **202***d* may include a group of holes **220**. Additionally, and as discussed herein, input areas **202***a*, **202***b*, **202***c*, **202***d*, when configured, may have boundaries defined by illuminated holes **220**. Although shown as being arranged in a grid geometry, it is understood that the group of holes **220** formed through contact portion **104** may be positioned in any geometry or configuration within contact portion **104**. Additionally, it is understood that holes **220** may be formed over the entire surface of contact portion **104**; however, only those holes **220** formed in input areas **202***a*, **202***b*, **202***c*, **202***d* may be visible by a user when a light is provided by light guide layer **218** and/or light source **222**, as discussed herein.

[0075] FIG. **11** shows a top view of electronic device **100** and input structure **200** configured as specific input areas corresponding to particular input devices or structures. As shown in FIG. **11**, and with continued reference to FIG. **10**, input areas **202***a*, **202***c*, **202***d* (see, FIG. **10**) may be configured to be interacted with by a user of electronic device **100**, where each input area **202***a*, **202***c*, **202***d* is configured as a distinct input device. Input area **202***b* (see, FIG. **10**) may not be configured as an input device, and therefore may be deactivated or selectively inoperable for electronic device **100**. Further, each of the input areas may be different, unique parts